

What is claimed is:

1. A method for manufacturing light emitting diode devices comprising the steps of:

5 preparing a substrate aggregation having a plurality of divisions;

mounting a plurality of LEDs on the substrate aggregation at the divisions;

forming a transparent layer on the substrate aggregation;

10 removing the transparent layer between adjacent divisions to form an individual transparent layer at each of the divisions and to form a groove around the individual transparent layer;

15 filling the groove with a reflector material to form a reflector layer; and

cutting the reflector layer and the substrate so as to form a reflector film on the outside wall of the individual transparent layer, thereby forming a plurality of LED devices.

20 2. The method according to claim 1 wherein the divisions are arranged in matrix.

3. The method according to claim 1 wherein the transparent layer and the reflector layer are made of same kind of resin.

25 4. The method for manufacturing light emitting diode devices comprising the steps of:

preparing a substrate aggregation having a plurality of divisions;

mounting a plurality of LEDs on the substrate

aggregation at the divisions;

forming an individual transparent layer at each of the divisions by molding;

5 filling a groove formed between adjacent individual transparent layer with a reflector material to form a reflector layer; and

cutting the reflector layer and the substrate so as to form a reflector film on an outside wall of the individual transparent layer, thereby forming a plurality of LED devices.

10 5. A light emitting diode device comprising a substrate made of resin;

an LED mounted on the substrate;

a transparent layer made of transparent resin and sealing LED; and

15 a reflector film made of same kind of resin as the resin of the transparent layer and formed around outside wall of the transparent layer.